

Ball-Bond ArrangementAbstract

5 A ball-bond arrangement comprising an aluminum bond pad of a semiconductor device and a wire ball-bonded to the aluminum bond pad, wherein the wire has a diameter of 10 to 80 μm and comprises a core consisting of a copper alloy consisting of 0.05 to 3 wt.-% of palladium and/or platinum with copper as the remainder to make up 100 wt.-%.

[No figure]